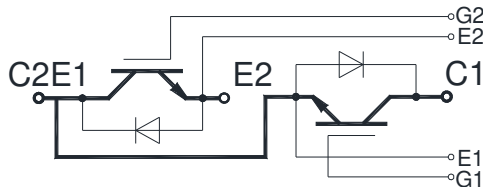




MRI150.17

2 in 1 IGBT Modules



Features:

- High short circuit capability, self limiting short circuit current
- IGBT CHIP (Highly rugged SPT+ design)
- $V_{CE(sat)}$ with positive temperature coefficient
- Ultra Low Loss, High Ruggedness
- Free wheeling diodes with fast and soft reverse recovery

Typical Applications:

- AC motor control
- Inverter and power supplies
- Motion/servo control
- Photovoltaic/Fuel cell

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V_{CES}	Collector-Emitter voltage	$T_j=25^\circ\text{C}$			1700	V
V_{GES}	Gate-Emitter voltage	$T_j=25^\circ\text{C}$			± 20	V
I_c	Collector current	$T_C=25^\circ\text{C}, T_{jmax}=175^\circ\text{C}$			225	A
		$T_C=100^\circ\text{C}, T_{jmax}=175^\circ\text{C}$			150	A
I_{CP}		$t_p=1\text{ms}$			300	A
P_C	Collector power dissipation	$T_j=175^\circ\text{C}, 1\text{ device}$			1071	W
T_j	Junction temperature	/			175	$^\circ\text{C}$
T_{stg}	Storage temperature	/	-40		125	$^\circ\text{C}$
V_{iso}	Isolation between terminal and copper base	$T_j=25^\circ\text{C}, \text{AC: } 1\text{minute}$	4000			V
Screw torque	Mounting(M6)	/	3.0		5.0	N·m
	Terminals(M6)	/	2.5		5.0	N·m
I_{CES}	Zero gate voltage collector current	$T_j=25^\circ\text{C}, V_{CE}=1700\text{V}, V_{GE}=0\text{V}$			1	mA
		$T_j=150^\circ\text{C}, V_{CE}=1700\text{V}, V_{GE}=0\text{V}$			10	mA
I_{GES}	Gate-Emitter leakage current	$T_j=25^\circ\text{C}, V_{CE}=0\text{V}, V_{GE}=\pm 15\text{V}$	-500		500	nA
$V_{GE(th)}$	Gate-Emitter threshold voltage	$V_{CE}=V_{GE}, I_c=6\text{mA}$	5.4	6.2	7.4	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^\circ\text{C}, V_{GE}=15\text{V}, I_c=150\text{A}$		2.3	2.7	V
		$T_j=125^\circ\text{C}, V_{GE}=15\text{V}, I_c=150\text{A}$		2.65		V
		$T_j=150^\circ\text{C}, V_{GE}=15\text{V}, I_c=150\text{A}$		2.7		V
C_{ies}	Input capacitance	$T_j=25^\circ\text{C}, V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		10.2		nF
t_{on}	Turn-on time	$V_{CC}=900\text{V}, I_c=150\text{A}, V_{GE}=\pm 15\text{V}, R_G=7.5\Omega, \text{Inductive load}$	$T_j=25^\circ\text{C}$		255	ns
			$T_j=150^\circ\text{C}$		280	ns
t_r	Turn-off time		$T_j=25^\circ\text{C}$		105	ns
			$T_j=150^\circ\text{C}$		110	ns
t_{off}	Turn-off time	$V_{CC}=900\text{V}, I_c=150\text{A}, V_{GE}=\pm 15\text{V}, R_G=7.5\Omega, \text{Inductive load}$	$T_j=25^\circ\text{C}$		630	ns
			$T_j=150^\circ\text{C}$		830	ns
t_f	Turn-off time		$T_j=25^\circ\text{C}$		180	ns
			$T_j=150^\circ\text{C}$		310	ns
V_F	Forward on voltage	$T_j=25^\circ\text{C}, I_F=150\text{A}$		1.75	2.30	V
		$T_j=125^\circ\text{C}, I_F=150\text{A}$		1.85		V
		$T_j=150^\circ\text{C}, I_F=150\text{A}$		1.90		V
t_{rr}	Reverse recovery time	$T_j=150^\circ\text{C}, I_F=150\text{A}$		950		ns
$R_{th(j-c)}$	Thermal resistance(1 device)	IGBT			0.14	$^\circ\text{C/W}$
		FWD			0.24	$^\circ\text{C/W}$
W_t	Weight				300	g
Outline	454H3P					

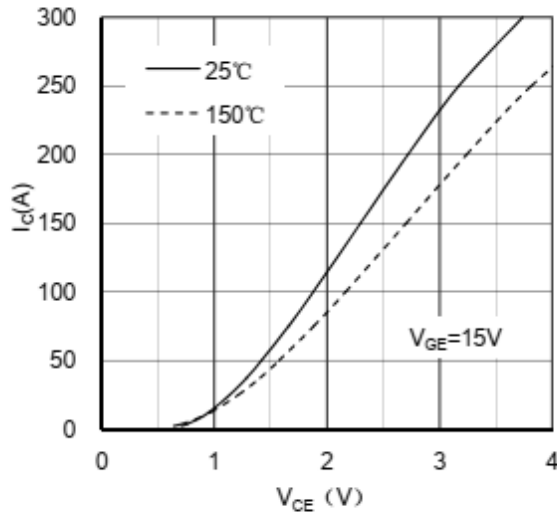


Figure 1. Typical Output Characteristics IGBT-inverter

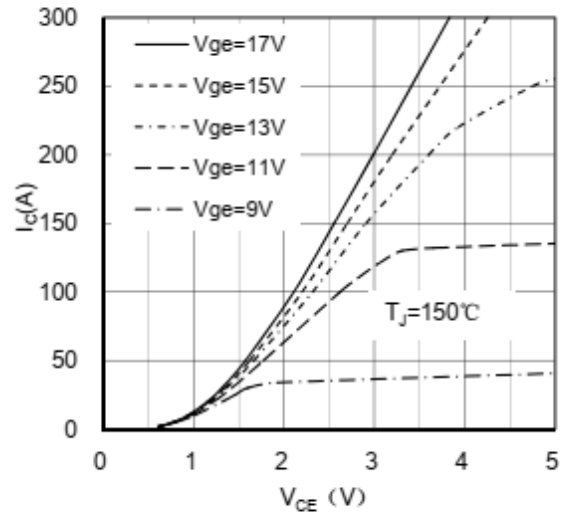


Figure 2. Typical Output Characteristics IGBT-inverter

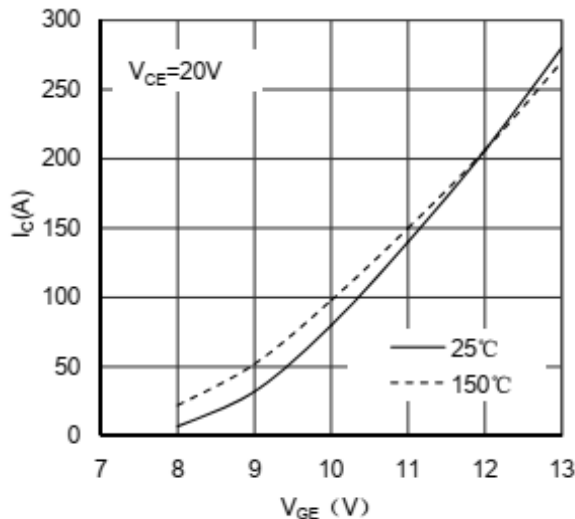


Figure 3. Typical Transfer characteristics IGBT-inverter

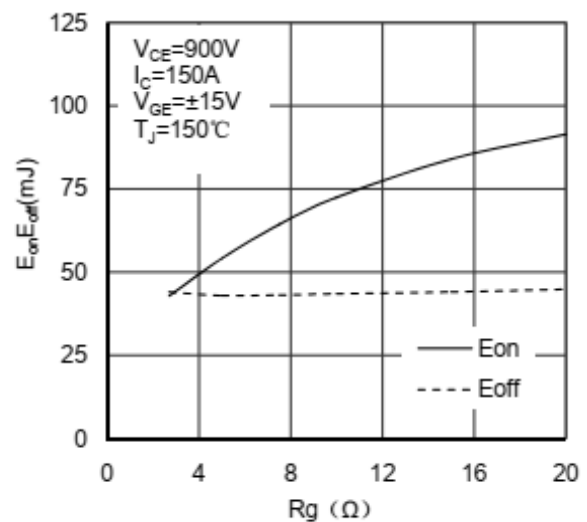


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

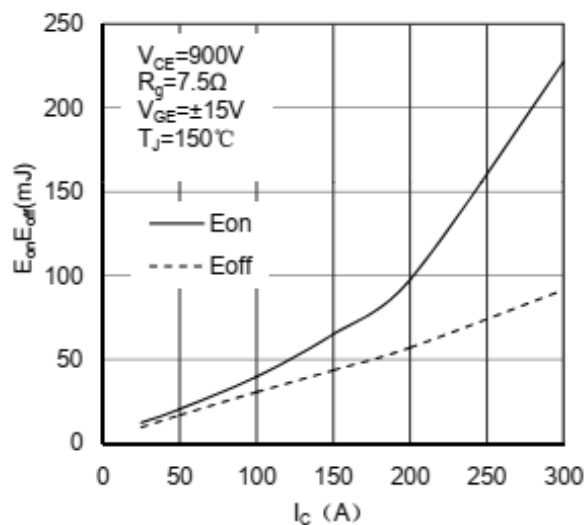


Figure 5. Switching Energy vs Collector Current IGBT-inverter

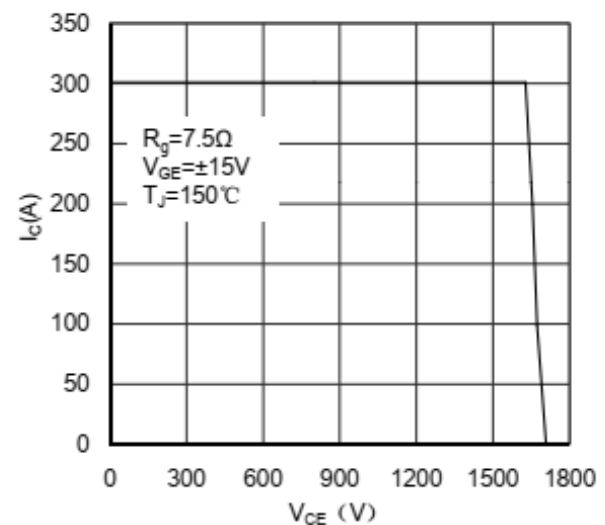


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

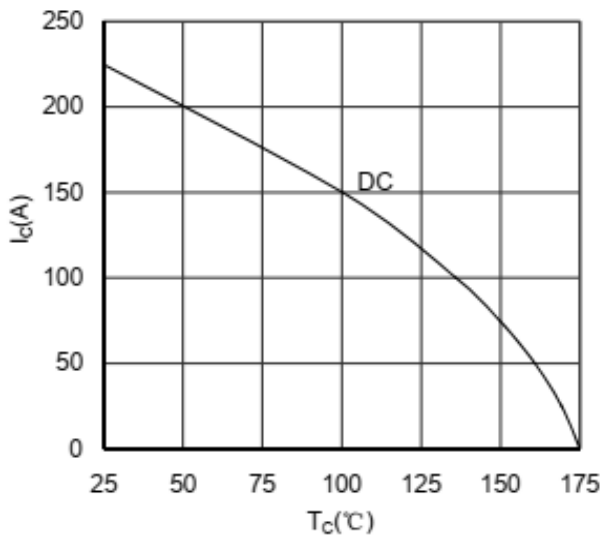


Figure 7. Collector Current vs Case temperature IGBT-inverter

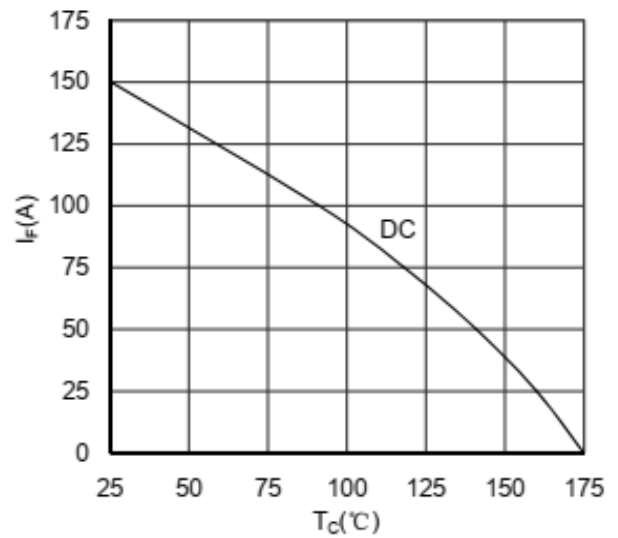


Figure 8. Forward current vs Case temperature Diode-inverter

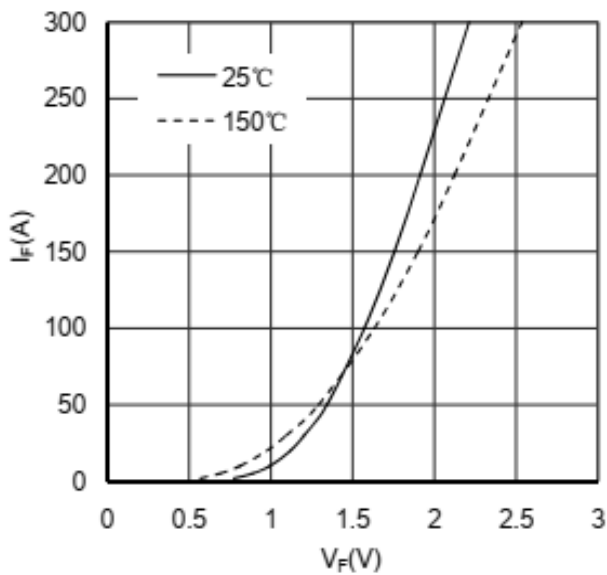


Figure 9. Diode Forward Characteristics Diode-inverter

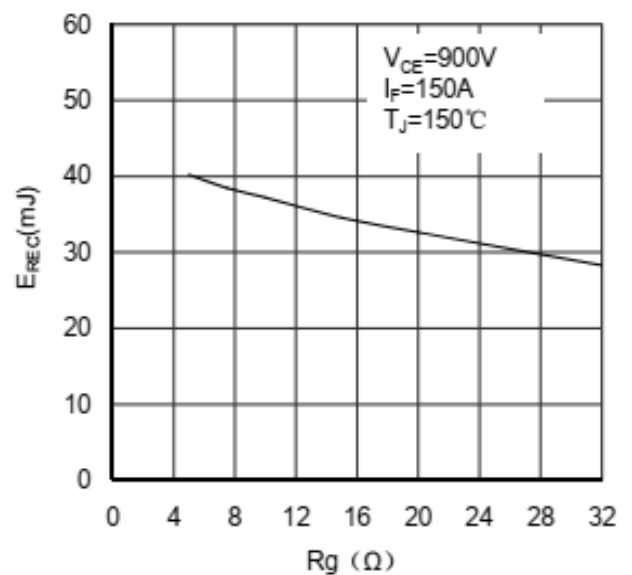


Figure 10. Switching Energy vs Gate Resistor Diode-inverter

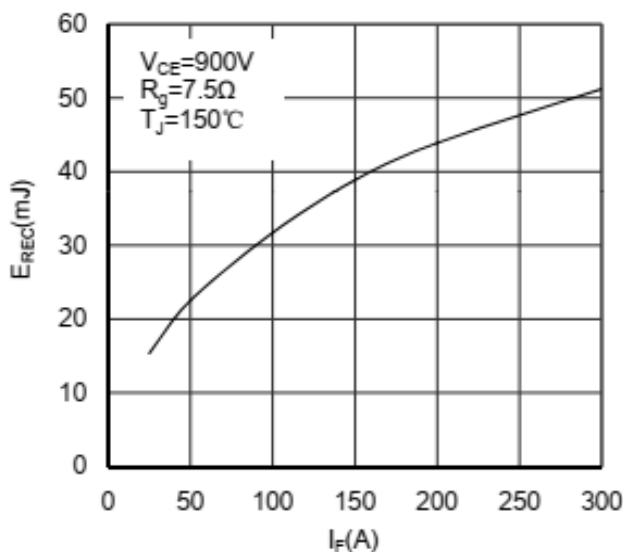


Figure 11. Switching Energy vs Forward Current Diode-inverter

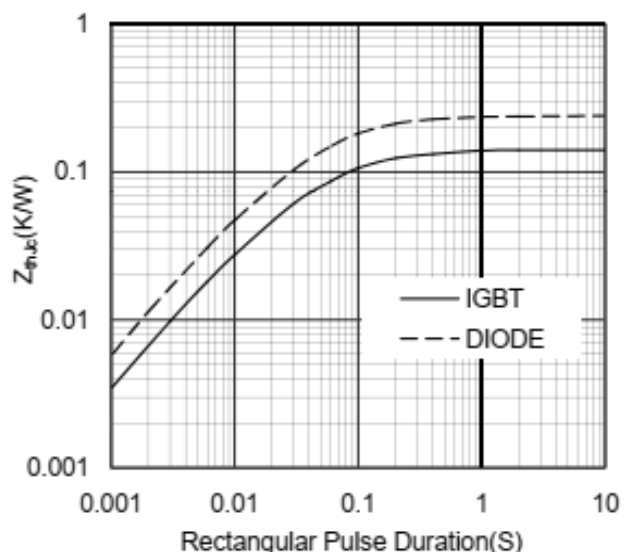
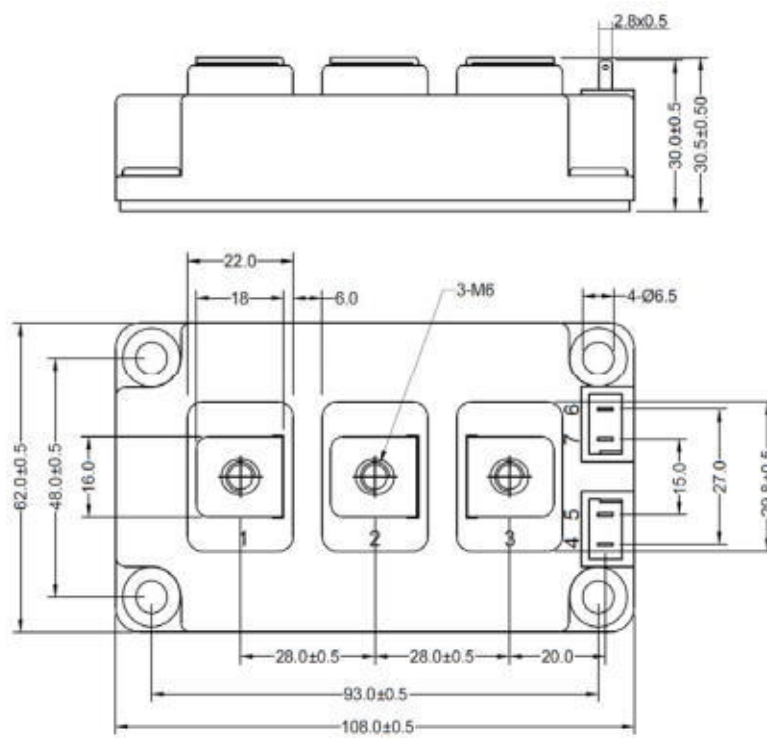


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

Outline:



Dimensions in (mm)